*** Material Composition - nRF52805-CAAA**

Material	Purpose	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogenous material
Polybenzoxazole1	Dielectric	Proprietary	----------	0.04518	100%
Polybenzoxazole2	Dielectric	Proprietary	----------	0.03962	100%
RDL Seed Layer	Seed Layer	Ti	7440-32-6	0.00026	3.93%
	Seed Layer	W	7440-33-7	0.00233	35.40%
	Seed Layer	Cu	7440-50-8	0.00399	60.67%
Copper	Interconnect	Cu	7440-50-8	0.07974	100%
UBM Seed Layer	Seed Layer	Ti	7440-32-6	0.00012	3.93%
	Seed Layer	W	7440-33-7	0.00106	35.40%
	Seed Layer	Cu	7440-50-8	0.00182	60.67%
Copper	UBM	Cu	7440-50-8	0.08170	100%
Solder Ball	Interconnect	Sn	7440-31-5	0.85568	95.50%
	Interconnect	Ag	7440-22-4	0.03584	4.00%
	Interconnect	Cu	7440-50-8	0.00448	0.50%
Die	Circuit	Si	7440-21-3	4.31801	100%
Top Surface Laminate	Mark Surface	Proprietary	----------	0.22190	100%
			Package Weight (mg):	5.69	

PPM	% weight of substance per package
7938	0.794%
6960	0.696%
45	0.005%
409	0.041%
701	0.070%
14010	1.401%
21	0.002%
186	0.019%
319	0.032%
14354	1.435%
150338	15.034%
6297	0.630%
787	0.079%
758649	75.865%
38987	3.899%
% Total:	**100%**